

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.04048	100.0	0.67
Subtotal				0.04048	100	0.67
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.013	0.03	0.2151
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.013	0.03	0.2151
	Copper alloy	Iron (Fe)	7439-89-6	0.04332	0.1	0.717
	Copper alloy	Copper (Cu)	7440-50-8	43.25127	99.84	715.8528
Subtotal				43.32059	100	717
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.19926	4.0	36.4
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	8.24722	15.0	136.5
	Filler	Silica fused	60676-86-0	40.6863	74.0	673.4
	Flame retardant	Metal hydroxide		3.8487	7.0	63.7
Subtotal				54.98148	100	910
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.51048	100.0	25
Subtotal				1.51048	100	25
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00278	2.0	0.046
	Lead alloy	Silver (Ag)	7440-22-4	0.00347	2.5	0.0575
	Lead alloy	Lead (Pb)	7439-92-1	0.13271	95.5	2.1965
Subtotal				0.13896	100	2.3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00801	100.0	0.13254
Subtotal				0.00801	100	0.13254
Total				100	100	1655.10254

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